

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/12/2022

Details for "TPS781250200DDCR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TPS781250200DDCR	NIPDAU	Level-2-260C-1 YEAR	Ext-Mfg	DDC 5	2.9x1.6x0.85	18.8

***Total Device Mass**

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Precious Metals	Gold	7440-57-5	0.042879	100	1000000	0.22756	2276
Sub-Total			0.042879	100	1000000	0.22756	2276
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.165238	75.000113	750001	0.876922	8769
Thermoplastics	Epoxy	85954-11-6	0.055079	24.999887	249999	0.292306	2923
Sub-Total			0.220317	100	1000000	1.169228	11692
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	11.51006	97.443786	974438	61.084172	610842
Copper and Its Alloys	Iron	7439-89-6	0.277507	2.349365	23494	1.472736	14727
Copper and Its Alloys	Phosphorus	7723-14-0	0.009701	0.082128	821	0.051483	515
Zinc and Its Alloys	Zinc	7440-66-6	0.014732	0.124721	1247	0.078183	782
Sub-Total			11.812	100	1000000	62.686575	626866
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.155046	95.120245	951202	0.822833	8228
Precious Metals	Gold	7440-57-5	0.001271	0.779755	7798	0.006745	67
Precious Metals	Palladium	7440-05-3	0.006683	4.1	41000	0.035467	355
Sub-Total			0.163	100	1000000	0.865045	8650
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	5.196911	86.999999	870000	27.580135	275801
Other Plastics and Rubber	Carbon Black	1333-86-4	0.005973	0.099992	1000	0.031699	317
Thermoplastics	Epoxy	85954-11-6	0.770577	12.900009	129000	4.089471	40895
Sub-Total			5.973461	100	1000000	31.701305	317013
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.631293	100	1000000	3.350288	33503
Sub-Total			0.631293	100	1000000	3.350288	33503
Total			18.84295			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component. The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/eoinfo
 Created on: 06/12/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.